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Jiangsu Xinde Semiconductor Technology Co., Ltd.
江蘇芯德半導體科技股份有限公司

(A joint stock company incorporated in the People's Republic of China with limited liability)

(Stock Code: 7672)

ANNOUNCEMENT ON LITIGATION

This announcement is made by the board of directors (the "**Board**") of Jiangsu Xinde Semiconductor Technology Co., Ltd. (the "**Company**") pursuant to Rule 13.09 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited (the "**Listing Rules**") and the Inside Information Provisions (as defined in the Listing Rules) under Part XIVA of the Securities and Future Ordinance (Chapter 571 of the Laws of Hong Kong).

I. BASIC INFORMATION ON THE LITIGATION

On 18 November 2026, the Company received six statements of complaint (Case Nos.: (2026) Su 01 Min Chu 1865, (2026) Su 01 Min Chu 1866, (2026) Su 01 Min Chu 1867, (2026) Su 01 Min Chu 1868, (2026) Su 01 Min Chu 1869 and (2026) Su 01 Min Chu 1870) served by the Nanjing Intermediate People's Court of Jiangsu Province. According to the six statements of complaint, the plaintiff, Jiangyin Changdian Advanced Packaging Co., Ltd. ("**Changdian Advanced**"), filed claims against the Company for infringement of six invention patents (the "**Claims**").

In the statements of complaint, Changdian Advanced, as the patentee of six separate invention patents, alleges that certain technologies of the Company fall within the scope of protection of the asserted patents. Changdian Advanced demands against the Company that injunctive relief be granted to stop manufacture, offer-for-sale and sale of allegedly infringing chip-packaging products, plus compensation for economic losses and enforcement costs totalling approximately RMB360 million, and payment of all litigation fees.

II. IMPACT OF THE LITIGATION ON THE COMPANY

The Company has sought legal advice in respect of the merits of the Claims. The Company's litigation counsel is of the view that, based on the existing litigation evidence, the technical features involved in the Claims are neither identical nor equivalent to the patent claims of the asserted patents, and therefore do not fall within the scope of protection of the asserted patents, and that the Claims are without factual and legal basis. As at the date of this announcement, no hearing has been held in respect of the litigation. The litigation is not expected to have a material adverse impact on the Company's current production and operations. The Company will take every possible step to protect the interests of the Company as well as the interests of the shareholders and potential investors of the Company. The Company will fulfil its disclosure obligations in accordance with the progress of the litigation and applicable disclosure requirements.

Shareholders and potential investors of the Company are advised to exercise caution when dealing in the shares of the Company.

By order of the Board
Jiangsu Xinde Semiconductor Technology Co., Ltd.
Mr. Zhang Guodong
Chairman of the Board and Executive Director

Nanjing, Jiangsu, the PRC, 22 November 2026

As of the date of this announcement, the Board comprises: (i) Mr. Zhang Guodong, Mr. Pan Mingdong, Mr. Liu Yi and Dr. Long Xinjiang as executive directors; (ii) Ms. Wang Chuxuan and Ms. Yu Xiaolin as non-executive directors; and (iii) Ms. Jiao Jie, Dr. Wang Xiaomu and Mr. Li Quanxing as independent non-executive directors.